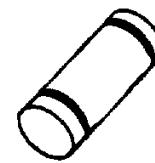


SMALL SIGNAL SCHOTTKY DIODE

DESCRIPTION

Metal to silicon junction diode featuring high breakdown, low turn-on voltage and ultrafast switching.
Primarily intended for high level UHF/VHF detection and pulse application with broad dynamic range.
Matched batches are available on request.



MINIMELF
(Glass)

ABSOLUTE MAXIMUM RATINGS (limiting values)

Symbol	Parameter	Value	Unit
V_{RRM}	Repetitive Peak Reverse Voltage	70	V
I_F	Forward Continuous Current	15	mA
P_{tot}	Power Dissipation	430	mW
T_{stg} T_j	Storage and Junction Temperature Range	-65 to 200 -65 to 200	°C
T_L	Maximum Temperature for Soldering during 15s	260	°C

THERMAL RESISTANCE

Symbol	Test Conditions	Value	Unit
$R_{th(j-l)}$	Junction-leads	400	°C/W

ELECTRICAL CHARACTERISTICS

STATIC CHARACTERISTICS

Symbol	Test Conditions	Min.	Typ.	Max.	Unit
V_{BR}	$T_{amb} = 25^\circ C$ $I_R = 10\mu A$	70			V
V_F^*	$T_{amb} = 25^\circ C$ $I_F = 1mA$			0.41	V
	$T_{amb} = 25^\circ C$ $I_F = 15mA$			1	
I_R^*	$T_{amb} = 25^\circ C$ $V_R = 50V$			0.2	μA

DYNAMIC CHARACTERISTICS

Symbol	Test Conditions	Min.	Typ.	Max.	Unit
C	$T_{amb} = 25^\circ C$ $V_R = 0V$ $f = 1MHz$			2	pF
τ	$T_{amb} = 25^\circ C$ $I_F = 5mA$ Krakauer Method			100	ps

* Pulse test: $t_p \leq 300\mu s$, $\delta < 2\%$.

Matched batches available on request. Test conditions (forward voltage and/or capacitance) according to customer specification.

Fig.1 : Forward current versus forward voltage at low level (typical values).

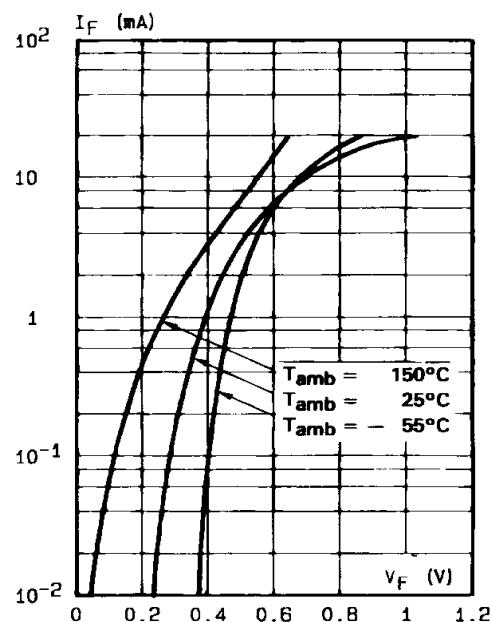


Fig.2 : Capacitance C versus reverse applied voltage V_R (typical values).

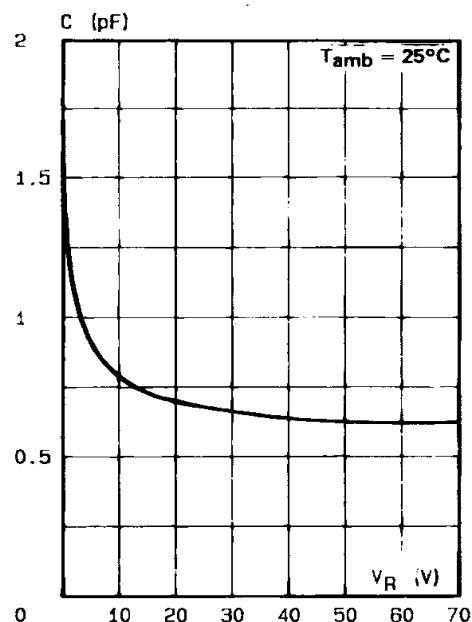


Fig.3 : Reverse current versus ambient temperature.

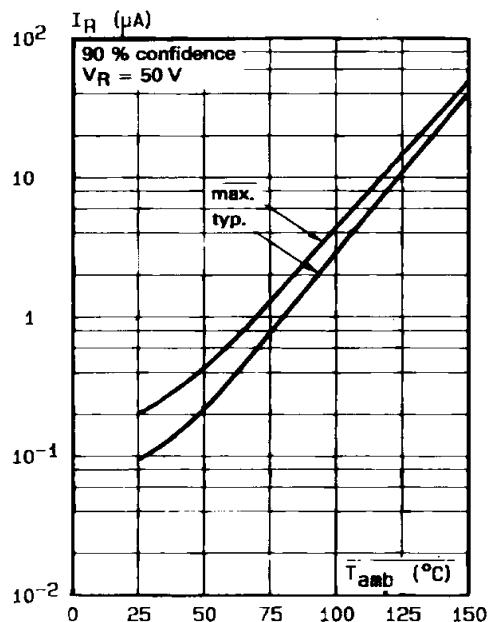
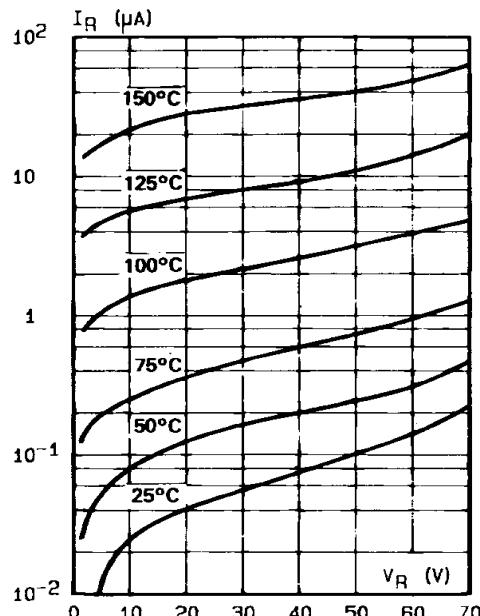
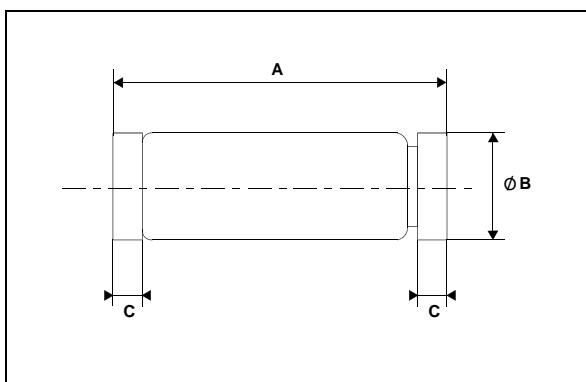


Fig.4 : Reverse current versus continuous reverse voltage (typical values).

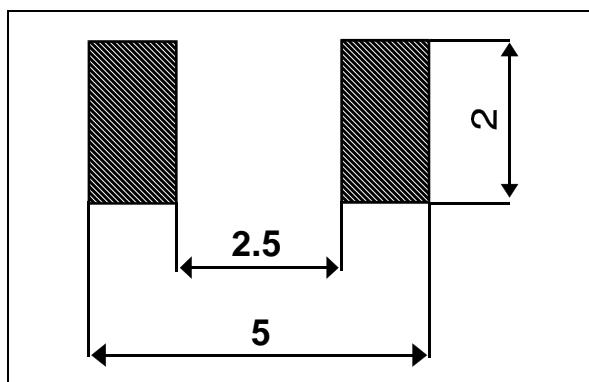


PACKAGE MECHANICAL DATA

MINIMELF Glass



FOOT PRINT DIMENSIONS (Millimeter)



REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	3.3	3.6	0.130	0.142
B	1.59	1.62	0.063	0.064
C	0.4	0.5	0.016	0.020

Marking: ring at cathode end.

Weight: 0.05g

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